

Electronic Patent Application Fee Transmittal

| Application Number: | 10500494 | | | |
|---|--|----------|--------|----------------------|
| Filing Date: | 27-Dec-2004 | | | |
| Title of Invention: | Method of forming copper interconnections for semiconductor integrated circuits on a substrate | | | |
| First Named Inventor/Applicant Name: | Hyung-Sang Park | | | |
| Filer: | Adeel S. Akhtar/Debbie Fonseca | | | |
| Attorney Docket Number: | 9907-007 | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-----------------------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Request for continued examination | 1801 | 1 | 790 | 790 |
| Total in USD (\$) | | | | 790 |